

WHAT IS CLAIMED IS:

1. An electronic circuit unit comprising:
a substrate on which a wiring pattern is provided;
5 electronic parts, including a semiconductor bare chip
disposed on the surface of the substrate;
a soft sealing resin provided on the surface of the
substrate so as to cover the electronic parts, wherein a
wire of the semiconductor bare chip is connected to the
10 wiring pattern and is covered with the soft sealing
resin; and
a protection member made of a resin harder than the
soft sealing resin having an upper wall which is a flat
outer surface and leg parts extending from the upper wall
15 to the substrate, wherein the protection member is
provided with the leg parts which are secured to the
substrate while covering the sealing resin.
2. The electronic circuit unit according to Claim 1,
20 wherein the protection member covers the entire exposed
surface of the substrate and the entire outer surface of
the soft sealing resin.
3. The electronic circuit unit according to Claim 1,
25 wherein the substrate comprises an inductor formed of a
thin film, a resistor formed of a thin film, and/or a
capacitor formed of a thin film thereon.

4. A method of manufacturing an electronic circuit unit, the method comprising the steps of:

preparing a substrate on which electronic parts including a semiconductor bare chip are provided and a
5 sealing resin composed of a soft resin material covering the electronic parts is provided; and

forming a protection member by filling or coating a resin that becomes harder than the sealing resin when solidifying, on the surface of the substrate and the
10 outer surface of the sealing resin so as to cover the surface of the substrate and the outer surface of the sealing resin,

wherein the protection member is provided with an upper wall having a flat outer surface and leg parts
15 extending from the upper wall and secured to the substrate.

5. The method according to Claim 4, further comprising providing a large plate substrate that is
20 formed by bonding a plurality of the substrates on which the sealing resin is formed,

wherein the resin that becomes harder than the sealing resin is filled or coated on the surface of the large plate substrate and the sealing resin, and the
25 large plate substrate and the resin are cut after the resin is solidified, thereby forming a single substrate having the protection member.

6. The method according to Claim 5, further comprising providing a jig exposing the surface of the large plate substrate and holding the resin that becomes hard therein,

5 wherein the resin that becomes hard is filled or coated on an inner side of the jig, and the resin is provided on large plate substrate, thereby solidifying the resin that becomes hard.